# C-Series H-Pin Socket

Accelerated life testing solution



C Series Socket is a modular burn-in socket with clamshell-style lid. The small footprint outline allows for a best-in-class range of package accommodations, from 0.5 mm body size up to 12 mm and optimal socket density per burn-in board.

Utilizing the H-Pin in the C-Series socket provides market leading electrical performance for all reliability testing requirements.

The modularity provides unmatched design flexibility and ensures no sacrifices are made in delivering a complete solution without compromising performance or reliability.

Burn-in sockets using H-Pin technology for high-reliability testing of next-generation IC packages

#### **Benefits**

- Design flexibility, in-house tooling and moulds allow for lowest cost of test.
- Extensive catalogue of standard components reduces cost and lead-time.
- ≥0.3 pitch accommodates a wide variety of application needs.
- Optimized thermal profile to end-use specification.

#### Feature options

- LCC, QFP, QFN, LGA, BGA, and WLCSP
- Spring-loaded plunger
- Heat sink
- HAST venting features
- Integrated thermal control with heater and sensor
- Reverse seating plane
- Package inserts for a variety of sizes
- High temperature materials for above 200°C applications

## C-Series socket specifications

#### Mechanical properties

Pitch: ≤0.35 mmPackage size:

LGA: 0.5 mm to 12 mm BGA: 0.5 mm to 9 mm

■ Pin count: LGA: 625 BGA/QNF: 750

■ Temperature: -55°C to 260°C

#### **Electrical properties**

■ Contact resistance: 35 mΩ

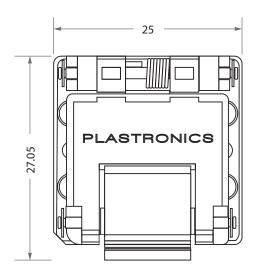
■ Current carrying capacity: up to 4 A

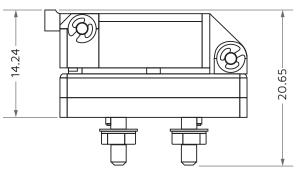
#### **Materials**

Contact: BeCu/Au platedSpring: SS/Au plated

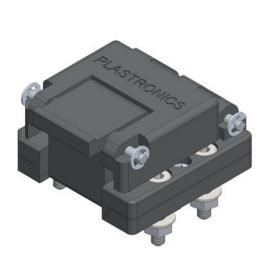
■ Socket: Engineering plastics

### C-Series socket dimensions





Dimensions are in mm.







Spring-loaded plunger

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